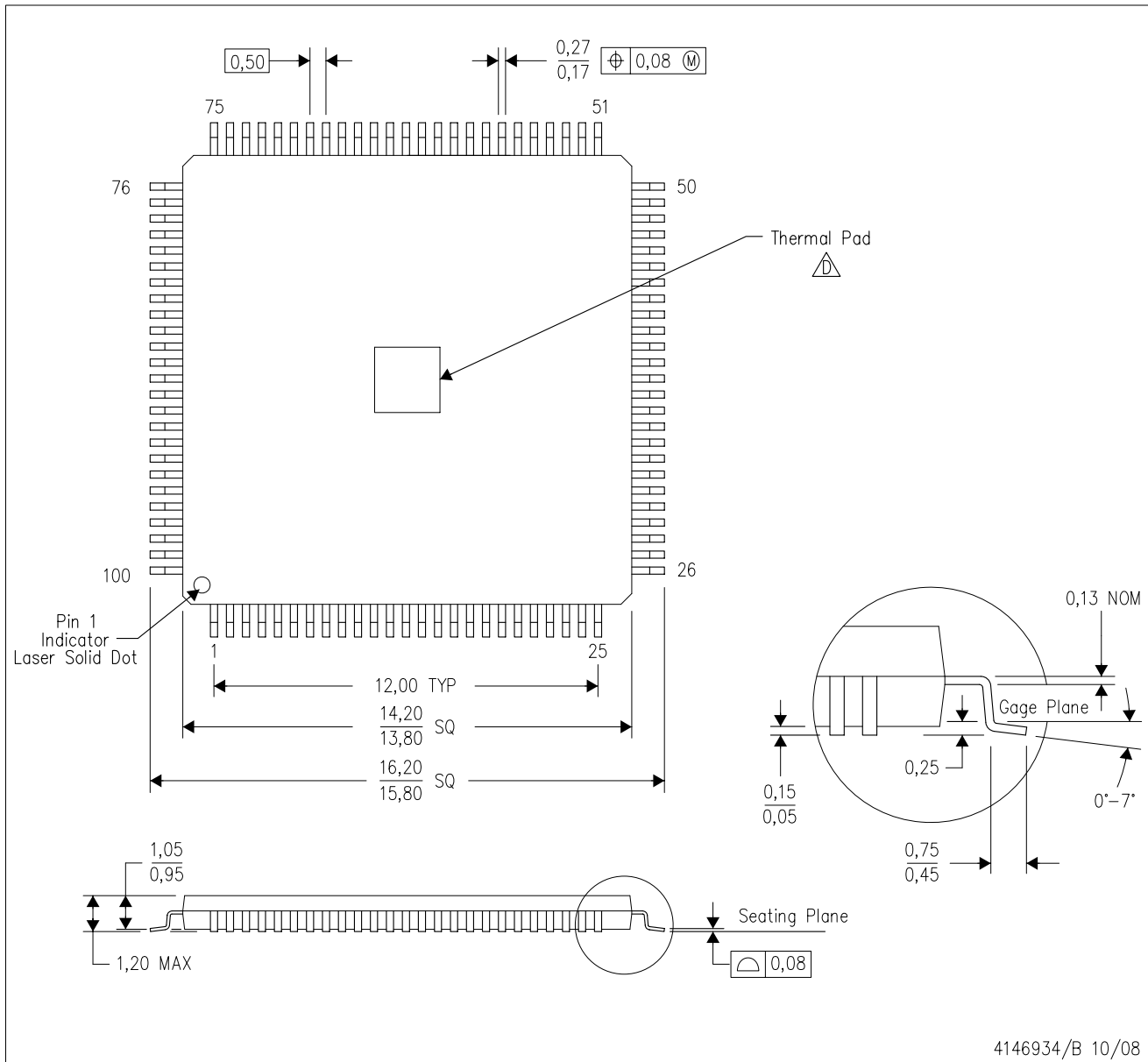


MECHANICAL DATA

PZD (S-PQFP-G100) PowerPAD™ PLASTIC QUAD FLATPACK (DIE DOWN)



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions include mold flash or protrusion.
 - △ This package is designed to be attached directly to an external heatsink. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - See the product data sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MS-026

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